

## LM8342

# Programmable TFT $V_{COM}$ Calibrator with Non-Volatile Memory

## General Description

The LM8342 is an integrated combination of a non-volatile register (7 bits EEPROM) and a DAC controlled current source. Using the LM8342, the  $V_{COM}$  calibration procedure is simplified by elimination of the potentiometer adjustment task. This adjustment task is currently performed at the factory using a trimmer adjustment tool and visual inspection.

The  $V_{COM}$  adjustment can be done electronically in production, using the I<sup>2</sup>C compatible interface. The factory operator can physically view the screen head-on (frontal viewing) when performing this step, easing manufacturing especially for large TFT panels.

The  $V_{COM}$  level is typically at half  $AV_{DD}$  (determined by R1 and R2) and is buffered by the actual  $V_{COM}$  driver. By controlling the level of  $I_{OUT}$ , the  $V_{COM}$  level can be tuned. The current level at the output of the LM8342 is a fraction (1/128 to 128/128) of a maximum current which is set by  $R_{SET}$  and an analog reference ( $AV_{DD}$ ). The actual fraction is determined by the 7-bit DAC. As a result, the output current of the LM8342 has a good temperature stability yielding a very stable  $V_{COM}$  adjustment. Controlling the DAC setting of the LM8342 is done via its I<sup>2</sup>C compatible interface. The actual DAC setting is stored in a volatile register. Using a "Write to EE" command the data can be stored permanently in the embedded EEPROM. At power on of the device, the EEPROM data is copied to the volatile register, setting the DAC. At any time, the data in the EEPROM can be changed again via the I<sup>2</sup>C compatible interface.

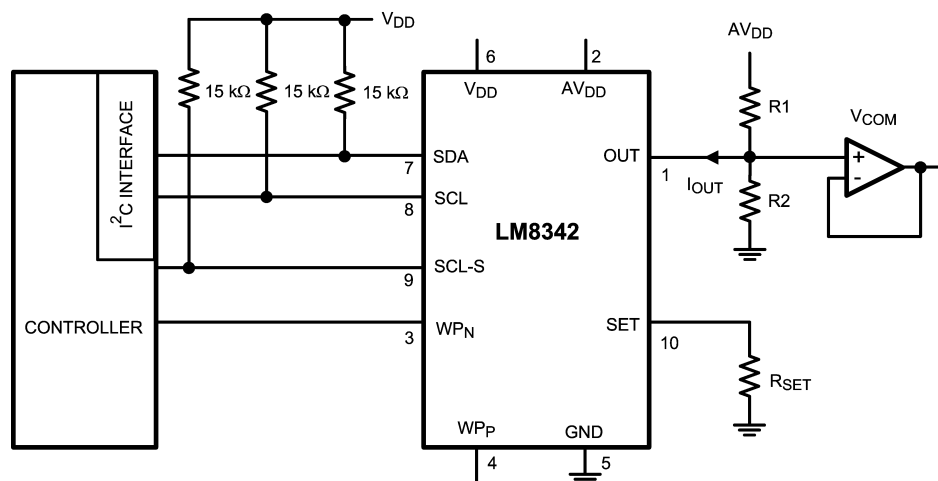
## Features

- I<sup>2</sup>C compatible programmable DAC to set the output current
- Guaranteed monotonic DAC
- Non-volatile memory to hold the setting
- EEPROM in system programmable
- No external programming voltage required
- Maximum interface bus speed is 400 kHz
- LLP-10 Package

## Applications

- TFT panel factory calibration
- Digital potentiometer
- Programmable current sink

## Typical Application



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**Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

ESD Tolerance (Note 2)

Human Body Model

SCL, SDA Pins: 4 kV

All Other Pins: 2.5 kV

Machine Model

250V

Supply and Reference Voltage

 $V_{DD}$ 

5V

 $AV_{DD}$ 

20V

Storage Temperature Range

-65°C to +150°C

Junction Temperature (Note 3)

+150°C

Soldering Information

Infrared or Convection (20 sec.)

235°C

Wave Soldering (10 sec.)

260°C

**Operating Ratings** (Note 1)

Operating Temperature Range (Note 4)

-40°C to 85°C

Digital Supply ( $V_{DD}$ ) (Note 5)

2.25V to 3.6V

Digital Supply ( $V_{DD}$ ) @ Programming

2.6V to 3.6V

Analog Reference ( $AV_{DD}$ ) (Note 5)

4.5V to 18V

Package Thermal Resistance  $\theta_{JA}$  (Note 3)

52°C/W

**Electrical Characteristics**

Unless otherwise specified, all limits are guaranteed for  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 3\text{V}$ ,  $AV_{DD} = 15\text{V}$ ,  $V_{OUT} = 1/2 AV_{DD}$  and  $R_{SET} = 10\text{ k}\Omega$ . **Boldface** limits apply at the temperature extremes. (Note 6)

Symbol	Parameter		Conditions	Min (Note 7)	Typ (Note 8)	Max (Note 7)	Units
Supply and Reference Current							
I <sub>DD</sub>	Supply Current				40	62	μA
AI <sub>DD</sub>	Analog Reference Current				8	13	μA
Control and Programming							
	SCL, SDA	Low Voltage				0.3 * V <sub>DD</sub>	V
		High Voltage		0.7 * V <sub>DD</sub>			
		Input Current				1	μA
		Frequency				400	kHz
	WP <sub>P</sub> /WP <sub>N</sub> Low Level					0.3 * V <sub>DD</sub>	V
	WP <sub>P</sub> /WP <sub>N</sub> High Level			0.7 * V <sub>DD</sub>			V
	WP <sub>N</sub> Input Current		V <sub>IH</sub> = 3.0V. (Note 9)		100		μA
R <sub>ON</sub>	SCL to SCL-S Switch Resistance				150		Ω
	SDA/SCL Input Capacitance				5		pF
	SCL-S Input Capacitance				3		pF
	SDA/SCL/SCL-S load current		No Supply, V <sub>SDA</sub> , V <sub>SCL</sub> = 3.6V			1	μA
	Programming Time		(Note 4)		200	300	ms
	I <sub>DD</sub> @ Programming				10	18	mA
	Programming Cycles			1000			
	Reading Cycles			10000			
Output							
	Output Settling Time		95% of Final Value		10		μs
	Start-Up Time				30		μs
V <sub>OUT</sub>	Output Voltage			V <sub>RSET</sub> + 0.5V		AV <sub>DD</sub>	V
I <sub>OUT</sub>	Output Current	Adjustability			7		Bits
		Differential Non-Linearity	AV <sub>DD</sub> = 10V, V <sub>OUT</sub> = 5V.	-1		1	LSB
		Zero Scale Error		-1		1.5	
		Full Scale Error		-4		4	
		Full Scale Range			5		100
	Voltage Drift V <sub>RSET</sub>			-1		1	LSB

## Electrical Characteristics (Continued)

**Note 1:** Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and test conditions, see the Electrical Characteristics tables.

**Note 2:** Human Body Model is 1.5 k $\Omega$  in series with 100 pF. Machine Model is 0 $\Omega$  in series with 200 pF.

**Note 3:** The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $\theta_{JA}$  and  $T_A$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} - T_A) / \theta_{JA}$ . All numbers apply for packages soldered directly onto a PC board.

**Note 4:** Programming temperature range 0°C to 70°C.

**Note 5:** When  $AV_{DD}$  is in the voltage range of 4.5V to 13V, the supply voltage  $V_{DD}$  can be in 2.25V to 3.6V range. When  $AV_{DD}$  is in the voltage range from 13V to 18V, the supply voltage  $V_{DD}$  is limited to the 2.6V to 3.6V range.

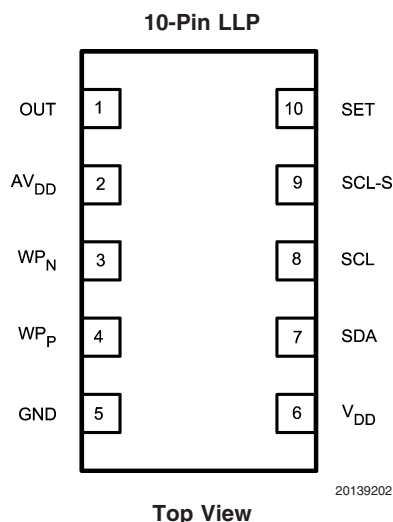
**Note 6:** Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that  $T_J = T_A$ . No guarantee of parametric performance is indicated in the electrical tables under conditions of internal self-heating where  $T_J > T_A$ .

**Note 7:** All limits are guaranteed by design or statistical analysis.

**Note 8:** Typical values represent the parametric norm at the time of characterization.

**Note 9:** On-Chip Pull Down Resistor of 30 k $\Omega$ .

## Connection Diagram



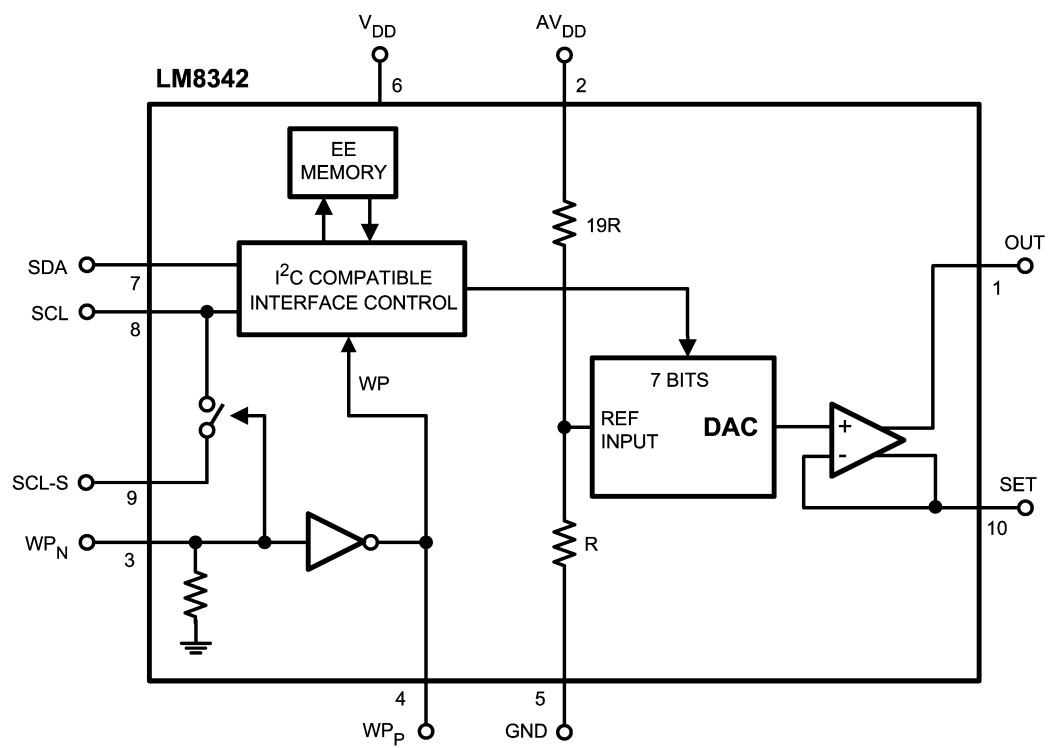
## Pin Descriptions

Pin Name	Pin #	Function				
OUT	1	Current sink output, adjustable in 128 steps. See Application Section for details.				
$AV_{DD}$	2	Analog reference voltage input				
$WP_N$	3	Write protect (input)				
			READ ( $I^2C$ )	WRITE→Reg	WRITE→EE	SCL Switch
		$WP_N$ = Low	yes	yes	no	open
		$WP_N$ = High	yes	yes	yes	closed
$WP_P$	4	Inverted $WP_N$ (output)				
GND	5	Ground				
$V_{DD}$	6	Supply voltage				
SDA	7	$I^2C$ compatible serial data input/output				
SCL	8	$I^2C$ compatible serial clock input				
SCL-S	9	Switched SCL connection. Serial clock input when $WP_N$ is set to high				
SET	10	Maximum output current adjustment pin (see block diagram)				

## Ordering Information

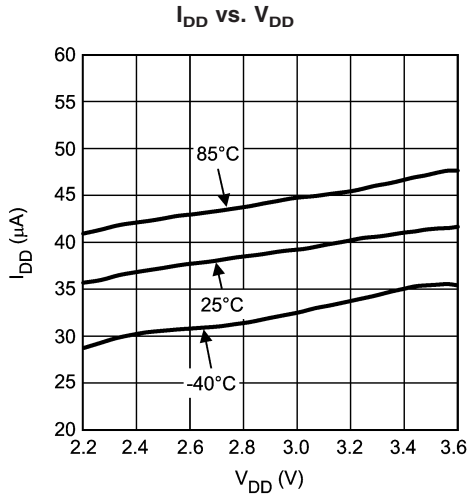
Package	Part Number	Package Marking	Transport Media	NSC Drawing
10-Pin LLP	LM8342SD	L8342	1k Units Tape and Reel	SDA10A
	LM8342SDX		4.5k Units Tape and Reel	

## Block Diagram

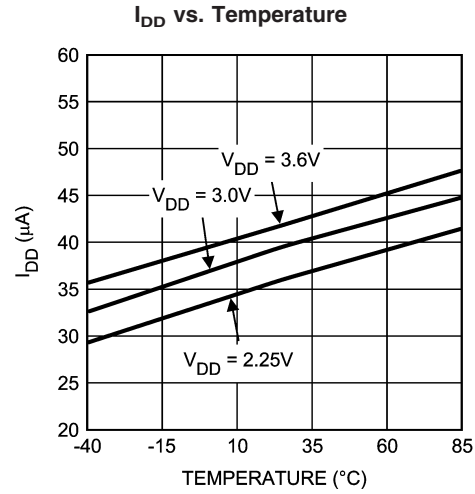


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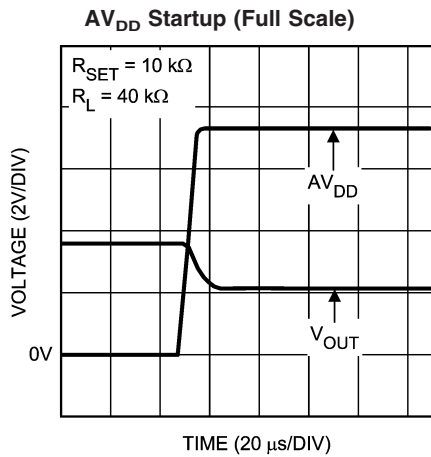
**Typical Performance Characteristics** At  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 3\text{V}$ ,  $AV_{DD} = 15\text{V}$ ,  $V_{OUT} = 1/2 AV_{DD}$  and  $R_{SET} = 10\text{ k}\Omega$ , unless otherwise specified.



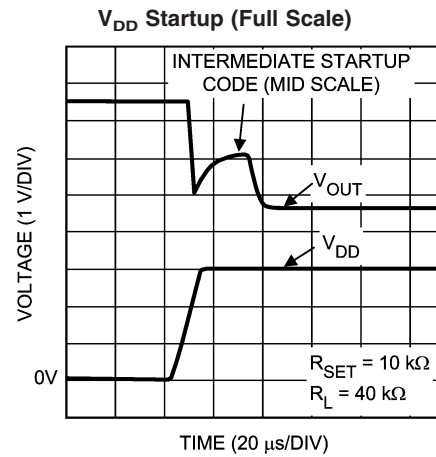
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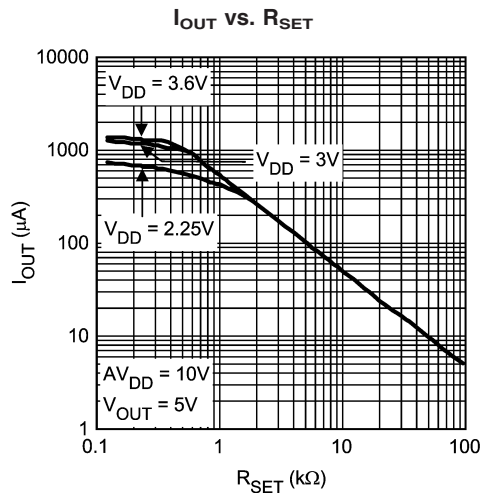
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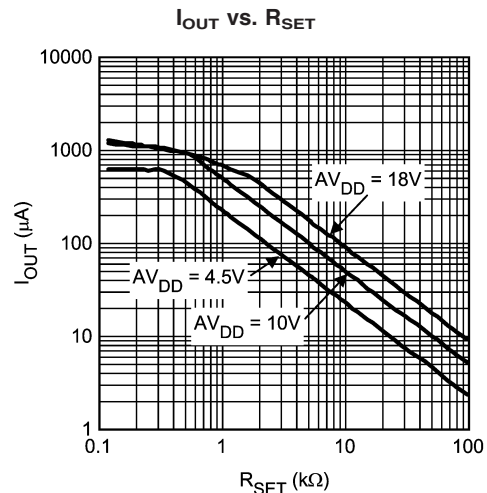
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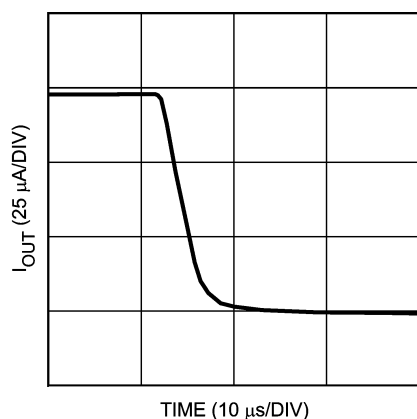
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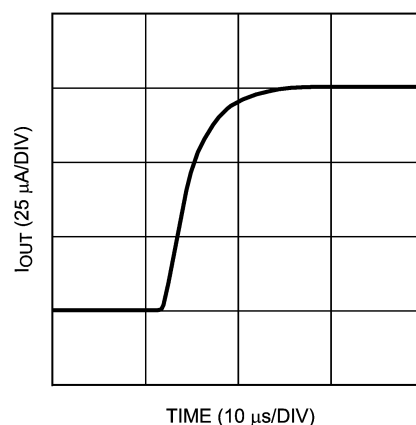
**Typical Performance Characteristics** At  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 3\text{V}$ ,  $AV_{DD} = 15\text{V}$ ,  $V_{OUT} = 1/2 AV_{DD}$  and  $R_{SET} = 10\text{ k}\Omega$ , unless otherwise specified. (Continued)

**$I_{OUT}$  Current Step Negative (Full Scale)**



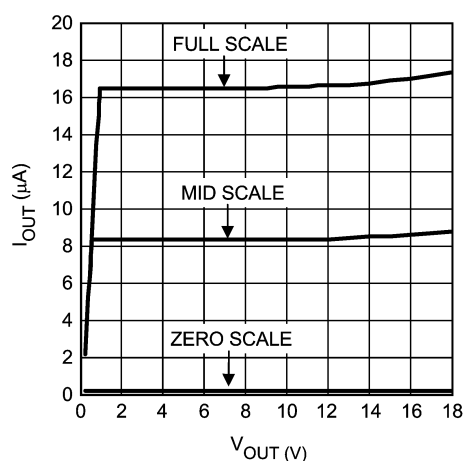
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**$I_{OUT}$  Current Step Positive (Full Scale)**



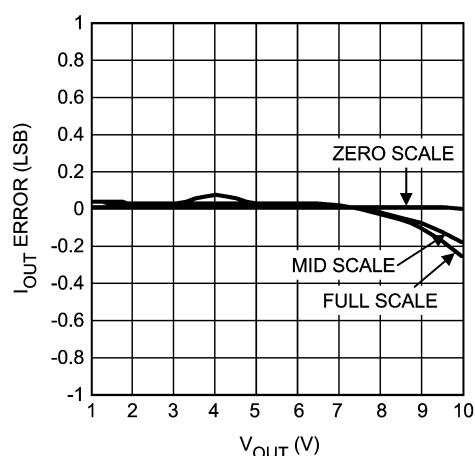
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**$I_{OUT}$  vs.  $V_{OUT}$**



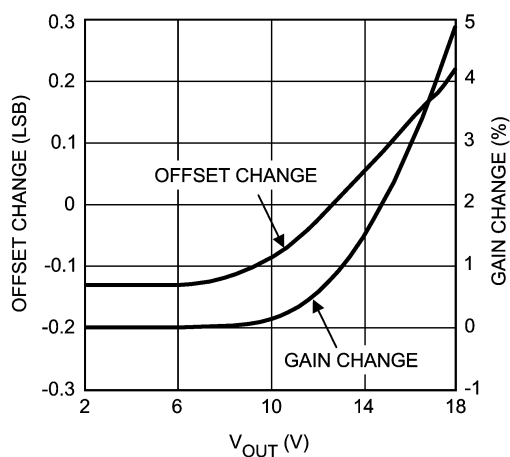
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**$I_{OUT}$  Error vs.  $V_{OUT}$**



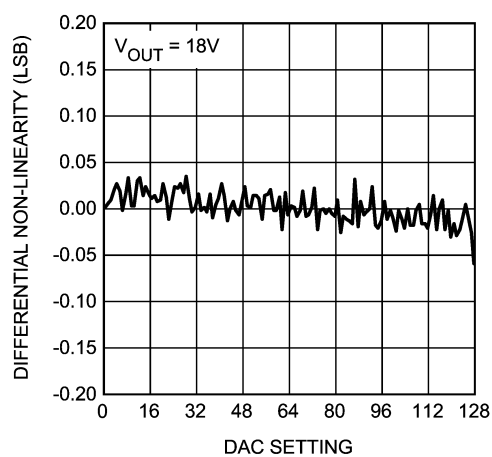
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**Gain & Offset Change vs.  $V_{OUT}$**



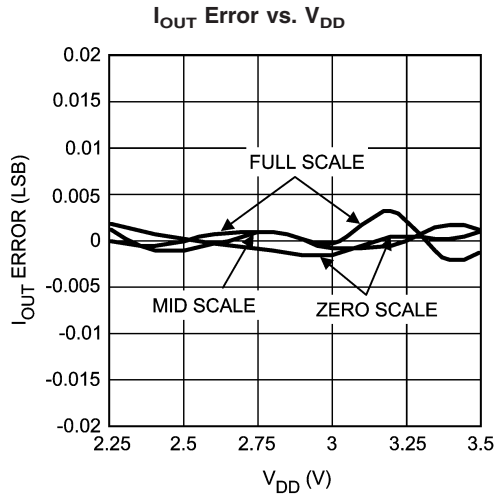
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**Differential Non-Linearity Error vs. DAC**  
( $V_{OUT} = 18\text{V}$ )

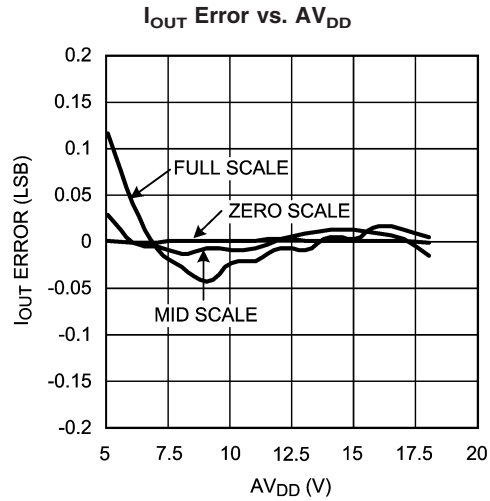


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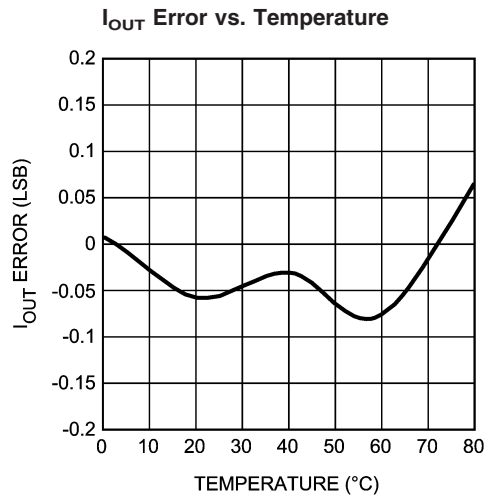
**Typical Performance Characteristics** At  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 3\text{V}$ ,  $AV_{DD} = 15\text{V}$ ,  $V_{OUT} = 1/2 AV_{DD}$  and  $R_{SET} = 10\text{ k}\Omega$ , unless otherwise specified. (Continued)



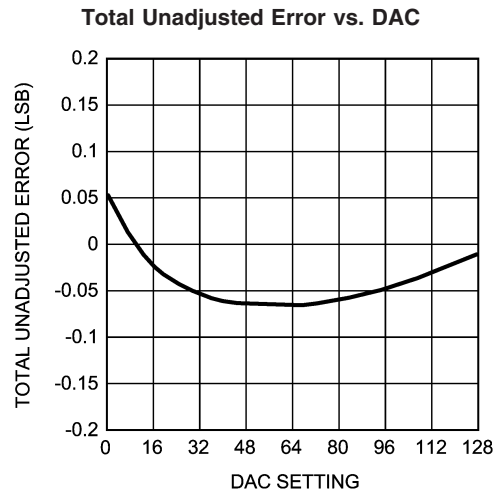
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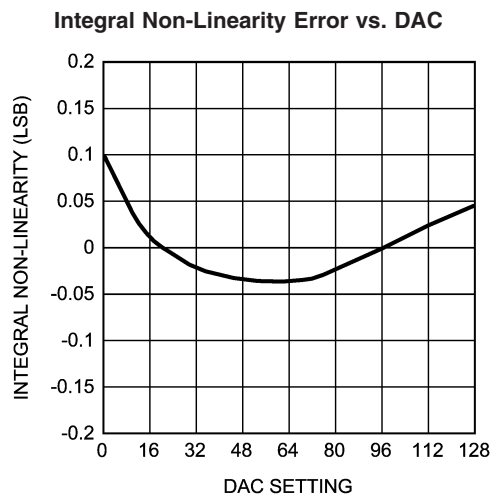
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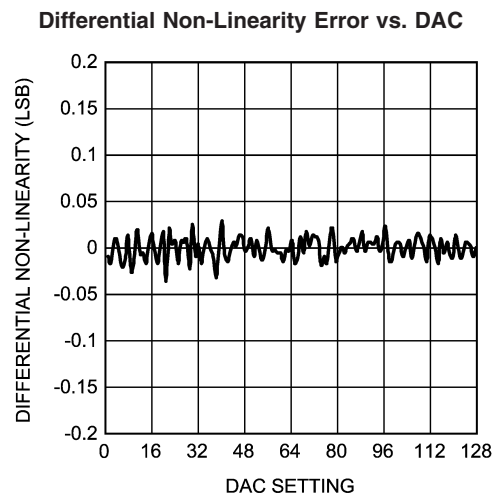
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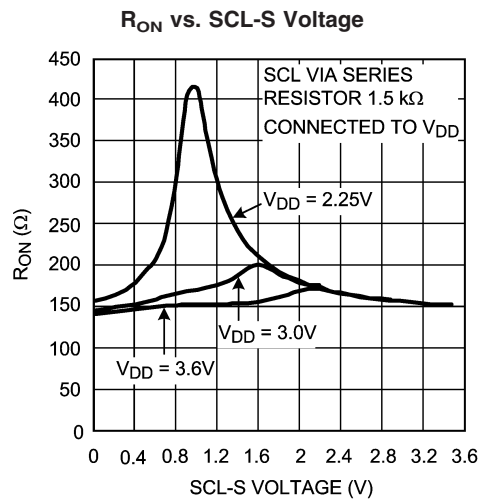
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## Typical Performance Characteristics

At  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 3\text{V}$ ,  $AV_{DD} = 15\text{V}$ ,  $V_{OUT} = 1/2 AV_{DD}$  and  $R_{SET} = 10\text{ k}\Omega$ , unless otherwise specified. (Continued)



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## Application Section

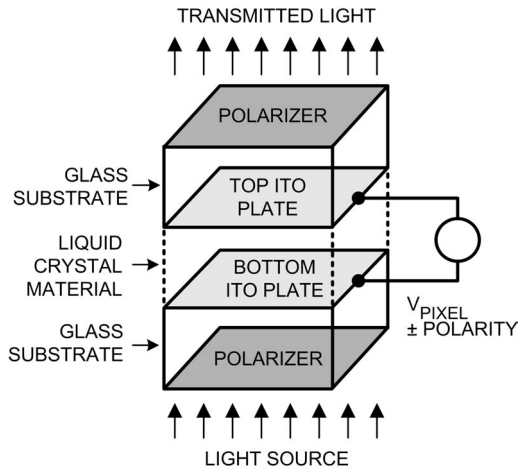
### INTRODUCTION

The LM8342 is an integrated combination of a digitally controlled current sink and a non-volatile register (7 bits EEPROM). Programming the register can be done using the I<sup>2</sup>C compatible interface. The LM8342 replaces the potentiometer adjustment, and thereby simplifies the  $V_{COM}$  calibration procedure. With the LM8342, the factory operator can physically view the screen head-on when performing this step, easing manufacturing especially for large TFT panel sizes.

The following sections discuss the principle of operation of a TFT-LCD and, subsequently give a description of how to use the LM8342, including the I<sup>2</sup>C compatible interface and control inputs. After this, two typical LM8342 configurations are presented. Subsequently an evaluation system is introduced, including a  $\mu$ C-board programming using the I<sup>2</sup>C compatible interface. At the end of this application section board layout recommendations are given.

### PRINCIPLE OF OPERATION OF A TFT-LCD

This section offers a brief overview of the principle of operation of TFT-LCD's. It gives a detailed description of how information is presented on the display. Further an explanation of how data is written to the screen pixels and how the pixels are selected is included.

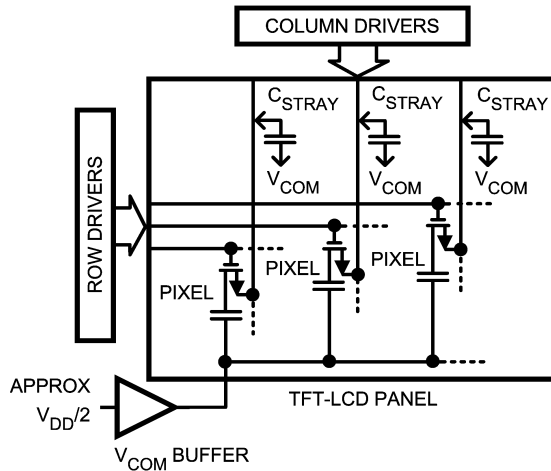


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**FIGURE 1. Individual LCD Pixel**

Figure 1 shows a simplified illustration of an individual LCD pixel. The top and bottom plates of a pixel consist of Indium-Tin Oxide (ITO), which is a transparent, electrically conductive material. ITO is at the inner surfaces of two glass sub-

strates that are the front and back glass panels of a TFT display. Sandwiched between two ITO plates is an insulating material (liquid crystal). Liquid crystals alter the polarization of light, depending on how much voltage ( $V_{PIXEL}$ ) is applied across the two plates. Polarizers are placed on the outer surfaces of the two glass substrates. In combination with the liquid crystal, the polarizers create an electrically variable light filter that modulates light transmitted from the back to the front of a display. A pixel's bottom plate is at the backside of a display where a light source is applied, and the top plate is at the front, facing the viewer. For most TFT displays, a pixel transmits the greatest amount of light when  $V_{PIXEL} \leq \pm 0.5V$ , and it becomes less transparent as the voltage increases with either positive or negative polarity.

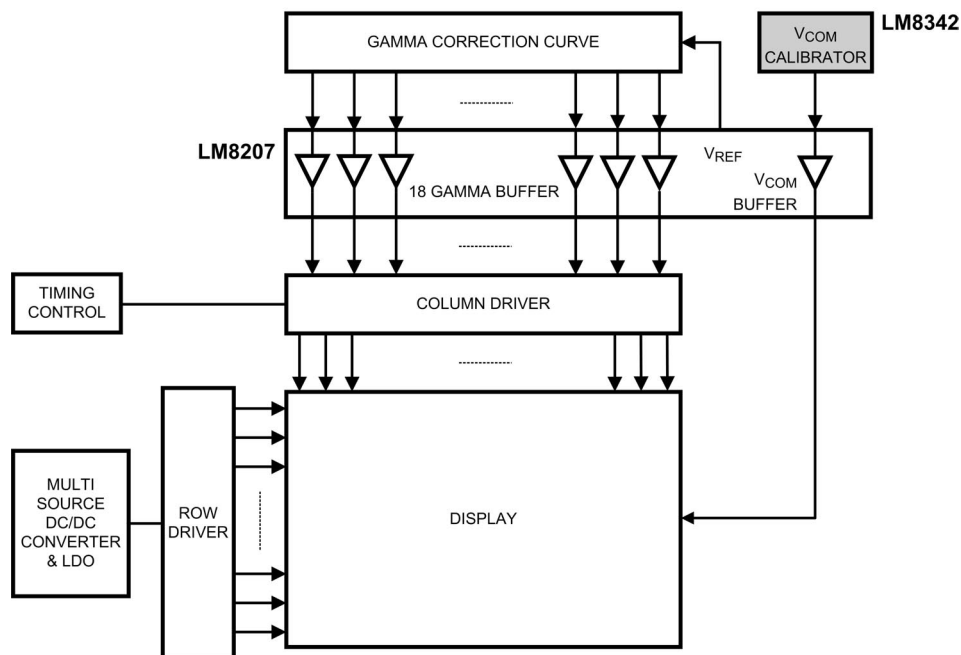


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**FIGURE 2. TFT Display**

Figure 2 shows a simplified diagram of a TFT display, showing how individual pixels are connected to the row, column and  $V_{COM}$  driver. Each pixel is represented by a capacitor with an NMOS transistor connected to its top plate. Pixels in a TFT panel are arranged in rows and columns. Row lines are connected to the NMOS gates, and column lines to the NMOS sources. The back plate of every pixel is connected to a common voltage called  $V_{COM}$ . The voltage applied to the top plates (i.e. Gamma Voltage) controls the pixel brightness. The column drivers supply this gamma voltage via the column lines, and 'write' this voltage to the pixels one row at a time. This is accomplished by having the row drivers selecting an individual row of pixels when the column drivers write the gamma voltage levels. The row drivers sequentially apply a large positive pulse (typically 25V to 35V) to each row line. This turns on the NMOS transistors connected to an individual row, allowing voltage from the column lines to be written to the pixels.

## Application Section (Continued)



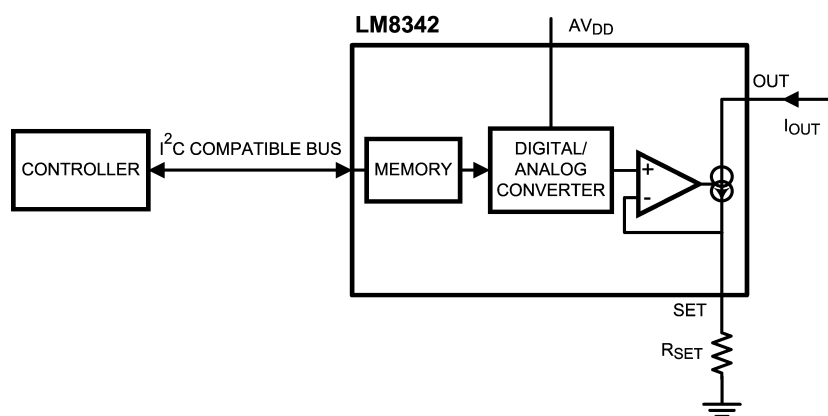
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FIGURE 3. TFT Panel Block Diagram

Figure 3 shows a block diagram of a TFT panel. The  $V_{COM}$  buffer supplies a common voltage ( $V_{COM}$ ) to all the pixels in a TFT panel. In general,  $V_{COM}$  is a DC voltage that is in the middle of the gamma voltage range. Screen performance can be optimized by tuning the  $V_{COM}$  voltage in the calibration procedure. Using the LM8342, the  $V_{COM}$  calibration procedure is simplified by elimination of the potentiometer adjustment task. This task is currently performed at the factory using a trimmer adjustment tool and visual inspection, when using a stable reference voltage and a potentiometer as a voltage divider to generate the  $V_{COM}$  voltage.

### PRINCIPLE OF OPERATION OF THE LM8342

The LM8342 is an integrated combination of a digitally controlled current sink and a non-volatile register (7 bits EEPROM). Writing data can be done using the I<sup>2</sup>C compatible interface. Data can be written to a volatile register and can also be stored in the non-volatile EEPROM. A simplified block diagram of the LM8342 is given in Figure 4.



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FIGURE 4. Block Diagram of the LM8342

## Application Section (Continued)

The maximum output current of the LM8342 can be defined using an external resistor  $R_{SET}$  in combination with an analog reference voltage  $AV_{DD}$ . This maximum current can be calculated using Equation (1).

$$I_{OUT\_MAX} = \frac{AV_{DD}}{20} \times \frac{1}{R_{SET}} \quad (1)$$

The operating range for the output current is given in the Electrical Characteristics table on page 2. Variations of the voltage reference  $AV_{DD}$  or the external resistor  $R_{SET}$  will affect this output current. Using a resistor with a low temperature coefficient is recommended.

The relative value of  $I_{OUT}$  with respect to the maximum current can be controlled digitally in 128 steps, using the internal DAC. This results in an output current described by Equation (2).

$$I_{OUT} = I_{OUT\_MAX} \times \frac{DAC_{10} + 1}{128} \quad (2)$$

Using the serial interface bus the operator can store the DAC value in the LM8342s 7-bits volatile register temporarily, or permanent in the EEPROM. During a start-up sequence the LM8342 will copy the contents of the EEPROM to the register setting the DC value.

### CONTROLLING THE DEVICE

The LM8342s current sink can be programmed using a serial interface bus. Additional functions (e.g. storing data in the EEPROM) can be controlled in combination with external inputs. Table 1 shows the pins of the LM8342 and gives a short functional description.

TABLE 1. Pin Descriptions

Pin name	Function
SDA & SCL (Serial interface bus)	The LM8342 output current can be controlled using the serial I <sup>2</sup> C compatible interface. This 2-Wire interface uses a clock and a data signal. New values can be written to the memory, or the current value can be read back from the device. The I <sup>2</sup> C compatible interface is discussed in more detail in the next chapter.
$AV_{DD}$	Analog reference voltage for the DAC.
$V_{DD}$	Supply voltage for both the analog and digital circuitry.
SET	An external resistor $R_{SET}$ connected to the SET pin determines the maximum output current, see Equation (1).
OUT	The output of the programmable current sink.
SCL-S	For in-circuit PCB testing, the LM8342 can use the additional Switched SCL signal (SCL-S) input for applying the SCL clock signal.

Pin name	Function
$WP_N$	“Write Protect Not” (Input) has 2 functions: 1. Prohibits programming the EEPROM, when low or left floating (Internal a pull-down resistor is connected) When $WP_N$ is set to a low level, only the volatile register is accessible. If $WP_N$ is set to a high level also the EEPROM is accessible. Actual writing to the EEPROM or the register is done using the “P-bit” in the serial communication. 2. $WP_N$ switches the SCL-S clock line. When $WP_N$ is set to a high level SCL-S is connected to SCL. The operator should turn off the original SCL clock.
$WP_P$	Write Protect Signal (Output). This is the inverted $WP_N$ signal.

### I<sup>2</sup>C SERIAL INTERFACE BUS

The LM8342 supports an I<sup>2</sup>C compatible communication protocol, which is a bidirectional bus oriented communication protocol. Any device that sends data on the bus is defined as a transmitter and the receiving device as a receiver. The I<sup>2</sup>C compatible communication protocol uses 2 wires: SDA (Serial Data Line) and SCL (Serial Clock Line). For both lines an external pull-up resistor, connected to the supply voltage, is required. The device controlling the bus is known as the master, and the device or devices being controlled are the slaves. Each device has its own specific address. The address of the LM8342 is 9E<sub>HEX</sub>. The master initiates the communication and provides the clock. The LM8342 always operates as a slave. A typical system using an I<sup>2</sup>C compatible interface bus is given in Figure 5.

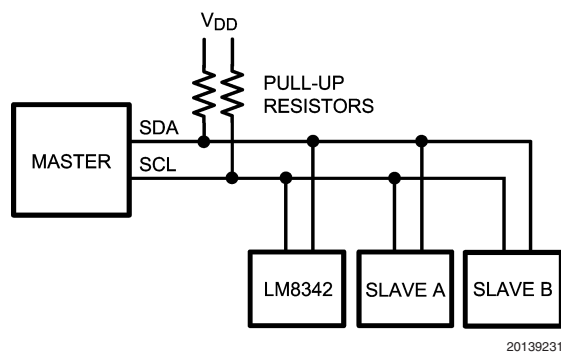


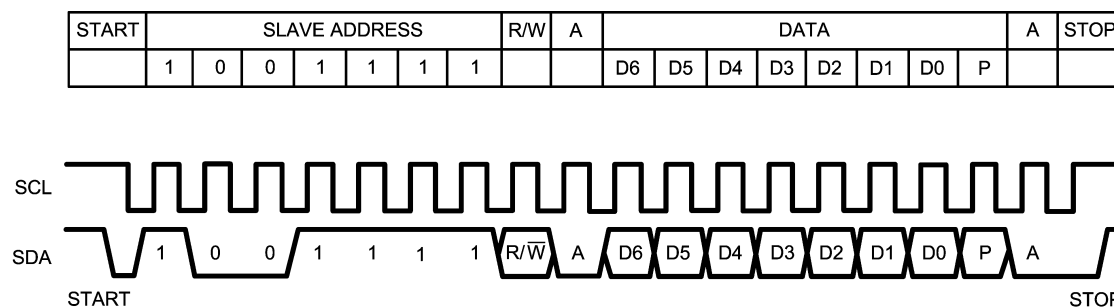
FIGURE 5. System Using an I<sup>2</sup>C compatible Bus

The LM8342 can be used in an I<sup>2</sup>C compatible system. All specifications of the LM8342, dealing with the interface bus, are guaranteed by design. Except for the bus speed, which is specified in the Electrical Characteristics table.

### KEY ASPECT OF I<sup>2</sup>C COMPATIBLE COMMUNICATION

In this section a brief overview is presented, discussing the key aspect of I<sup>2</sup>C compatible communication. Figure 6 shows the timing aspects of the I<sup>2</sup>C compatible serial interface.

## Application Section (Continued)



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**FIGURE 6. Timing Diagram**

The timing diagram shows the major aspect of the communication protocol and represents a typical data stream. In case a master wants to setup a data transfer, it tests if "the bus is busy." If it is not busy, then the master starts the data transfer by creating a "start data transfer" situation. Accordingly the corresponding receiver is selected by sending the appropriate "slave address." This receiver gives an "acknowledge" on recognizing its address on the bus. The master continues the data transfer by sending the data stream. Again the receiver gives an "acknowledge" after receipt. Depending on the amount of data the master will continue or create a "stop data transfer" situation. *Table 2* gives a more detailed description of the I<sup>2</sup>C compatible communication.

**TABLE 2. Detailed Description of I<sup>2</sup>C compatible Communication Definitions**

Bus not busy	The I <sup>2</sup> C compatible bus is not busy when both data (SDA) and clock (SCL) lines remain HIGH. The controller can initiate data transfer only when the bus is not busy.
Start Data Transfer	Starting from an idle state (bus not busy) a START condition consists of a HIGH to LOW transition of SDA while SCL is HIGH. All commands must start with a START condition.
Slave address	After generating a start condition, the master transmits a 7-bit slave address. (The LM8342 uses the 8th bit for selecting the R/W operation, but this does not affect the address.) The address for the LM8342 is 9E <sub>HEX</sub> .
R/W-bit	If the value of the R/W bit is HIGH, the data is read from the register of the LM8342. Otherwise the current DAC setting is written to the LM8342.

Acknowledge	A receive device, when addressed, is obliged to generate an "acknowledge" after the reception of each byte. The master generates an extra clock cycle that is associated with this acknowledge bit. The receiver has to pull down the SDA line during the acknowledge clock pulse so that the SDA line is stable LOW during the HIGH period of SCL, with respect to the SCL timing specifications.
Data byte	A data byte consists of 8 bits. 7 bits are used for the DAC setting of the LM8342. The 8th bit is known as the P-bit.
P-bit	The function of the P-bit depends on the Read/Write operation (R/W-bit). During a Read operation of the LM8342, the P-bit indicates the programming state of the EEPROM. During a Write operation, the register or both the register and the EEPROM of the LM8342 can be selected as destination. A more detailed description of the P-bit is given in <i>Table 3</i> .
Stop Data Transfer	A STOP condition consists of a LOW to HIGH transition of SDA while SCL is HIGH. All operations must be ended with a STOP condition.

### Application Section (Continued)

**TABLE 3. P-bit Truth Table**

Operation	P-bit	Description
Read	1	Programming Ready
Read	0	Programming Busy (don't turn off the device)
Write	1	Register Write
Write	0	EEPROM Write

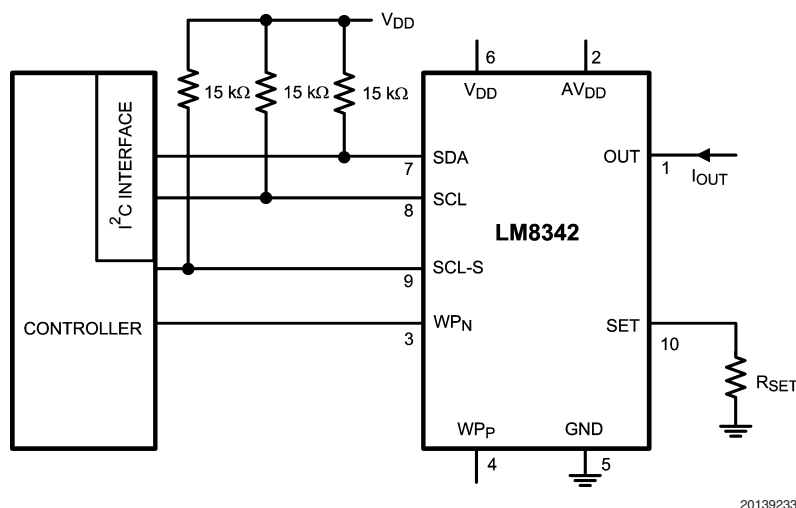
The LM8342 can be used in I<sup>2</sup>C compatible systems with clock speeds of up to 400 kbps (Fast mode). For low speed applications, an initial resistor value for the pull-up resistors is 15 k $\Omega$  is suitable. When increasing the speed of the interface bus, the user should decrease the value of the pull-up resistors.

## Typical Application

The following section discusses two typical applications for the LM8342. In the first application the LM8342 is used as a programmable current sink, for example to drive a programmable bias generator. In the second application the LM8342 is used to adjust the voltage level of a  $V_{COM}$  driver.

## PROGRAMMABLE CURRENT SINK

As described in the “Principle of Operation of the LM8342” section the LM8342 basically operates as a programmable current sink. *Figure 7* shows a general current sink application.



### FIGURE 7. Programmable Current Sink

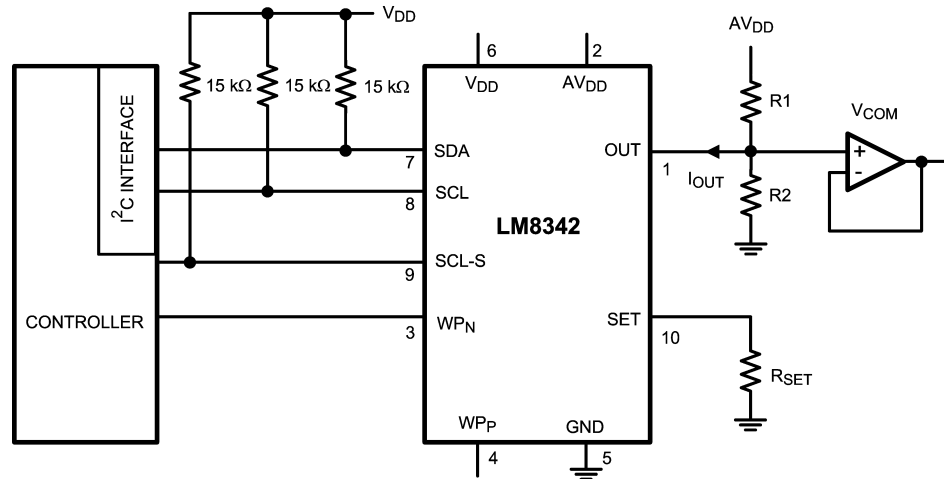
The output current of the LM8342 can be calculated using Equation (3).

$$I_{OUT} = \frac{AV_{DD}}{20} \times \frac{1}{R_{SET}} \times \frac{DAC_{10} + 1}{128} \quad (3)$$

## DRIVING A $V_{COM}$ LEVEL

Another typical application, given in *Figure 8*, is using the LM8342 to adjust the “voltage tap” of a resistive voltage divider. The  $V_{COM}$  driver buffers the “voltage tap” in this application.

## Typical Application (Continued)



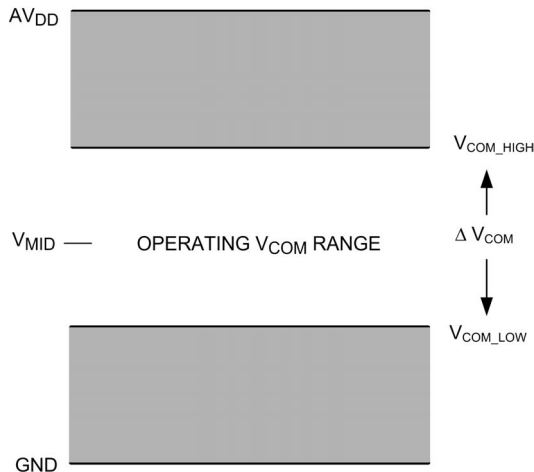
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**FIGURE 8. Typical Application Driving a  $V_{COM}$  Level**

The voltage level of the  $V_{COM}$  driver, for a general setting of ( $DAC_{10}$ ), is calculated using Equation (4).

$$V_{COM} = AV_{DD} \times \left( \frac{R_2}{R_1 + R_2} \right) \times \left( 1 - \frac{(DAC_{10} + 1) \times R_1}{128 \times R_{SET} \times 20} \right) \quad (4)$$

For calibrating the  $V_{COM}$  level (see Figure 8) the tuning range of the design needs to be aligned to the required  $V_{COM}$  tuning range ( $\Delta V_{COM}$ ). Figure 9 gives a graphical presentation of the desired voltage levels.



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**FIGURE 9.  $V_{COM}$  Voltage Levels**

Assume the calibrator needs to cover the voltage range given in Equation (5).

$$\Delta V_{COM} = V_{COM\_HIGH} - V_{COM\_LOW} \quad (5)$$

The limits of  $V_{COM}$  for  $DAC_{10} = 0$  (high limit) and  $DAC_{10} = 127$  (low limit) are given by:

$$V_{COM\_HIGH} = AV_{DD} \times \left( \frac{R_2}{R_1 + R_2} \right) \times \left( 1 - \frac{R_1}{128 \times R_{SET} \times 20} \right) \quad (6)$$

$$V_{COM\_LOW} = AV_{DD} \times \left( \frac{R_2}{R_1 + R_2} \right) \times \left( 1 - \frac{R_1}{R_{SET} \times 20} \right) \quad (7)$$

Using Equation (5), Equation (6), and Equation (7) the value for resistors  $R_1$  and  $R_2$  can be obtained, resulting in Equation (8) and Equation (9):

$$R_1 = \frac{40 \times R_{SET} \times \Delta V_{COM}}{AV_{DD} + \Delta V_{COM}} \quad (8)$$

and

$$R_2 = \frac{40 \times R_{SET} \times \Delta V_{COM}}{AV_{DD} - \Delta V_{COM}} \quad (9)$$

Table 4 gives an overview of resistor values for a typical value of  $AV_{DD}$ , and 2  $R_{SET}$  values. All settings are for a  $V_{COM}$  level at  $V_{MID} = \frac{1}{2} AV_{DD}$ , and a maximum variation of  $\Delta V_{COM}$ .

$$V_{MID} - \frac{1}{2} \Delta V_{COM} < V_{COM} < V_{MID} + \frac{1}{2} \Delta V_{COM} \quad (10)$$

## Typical Application (Continued)

**TABLE 4. Overview Resistor Values for Different  $R_{SET}$  Settings at  $AV_{DD} = 15V$**

$AV_{DD} = 15V$ ( $V_{COM}$ Level = 7.5 V)					
$R_{SET} = 10\text{ k}\Omega$			$R_{SET} = 45\text{ k}\Omega$		
$\Delta V_{COM}$ (V)	R1 ( $\Omega$ )	R2 ( $\Omega$ )	$\Delta V_{COM}$ (V)	R1 ( $\Omega$ )	R2 ( $\Omega$ )
$\pm 0.5$	25k	28.6k	$\pm 0.5$	113k	129k
$\pm 1$	47.1k	61.5k	$\pm 1$	212k	277k
$\pm 1.5$	66.7k	100k	$\pm 1.5$	300k	450k
$\pm 2$	84.2k	146k	$\pm 2$	379k	655k
$\pm 2.5$	100k	200k	$\pm 2.5$	450k	900k
$\pm 3$	114k	267k	$\pm 3$	514k	1.2M

### EVALUATION SYSTEM

For the LM8342 a complete evaluation system is available, including two boards. *Figure 10* gives a schematic representation.

- **LM8342 Evaluation Board**

This board demonstrates the functionality of the LM8342 using the I<sup>2</sup>C compatible interface for communication. The LM8342 can easily be demonstrated in 2 applications:

- Programmable current sink
- Programmable  $V_{COM}$  level driver

- **LM8342 Programmer Board**

This test board has dedicated functionality for communicating with the LM8342, using the I<sup>2</sup>C compatible interface. This board can operate in two different modes:

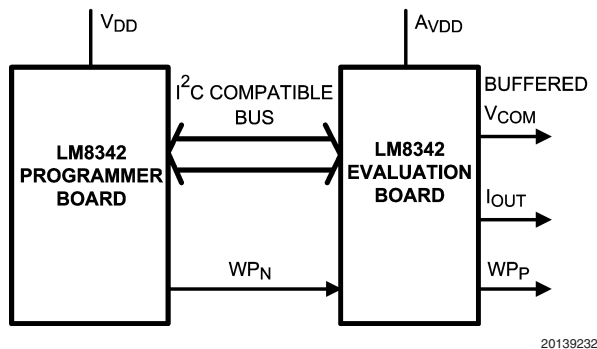
- **Write mode:** The digitized value of a potentiometer setting is written to the LM8342. The user can select on the programmer board to write the data to the register or to store the data in the EEPROM.
- **Read mode:** The board reads the stored values from the LM8342's EEPROM and presents this data onto a 3-digit display.

### LAYOUT RECOMMENDATIONS

A proper layout is necessary for optimum performance of the LM8342. A low impedance and proper ground plane (free of disturbances) is recommended, since a current of up to 10 mA can flow with HF contents during programming. The traces from the GND pin to the ground plane should be as short as possible. It is recommended to place decoupling capacitors close to the  $V_{DD}$  and  $AV_{DD}$  pins. Connections of these decoupling capacitors to the ground plane should be short.

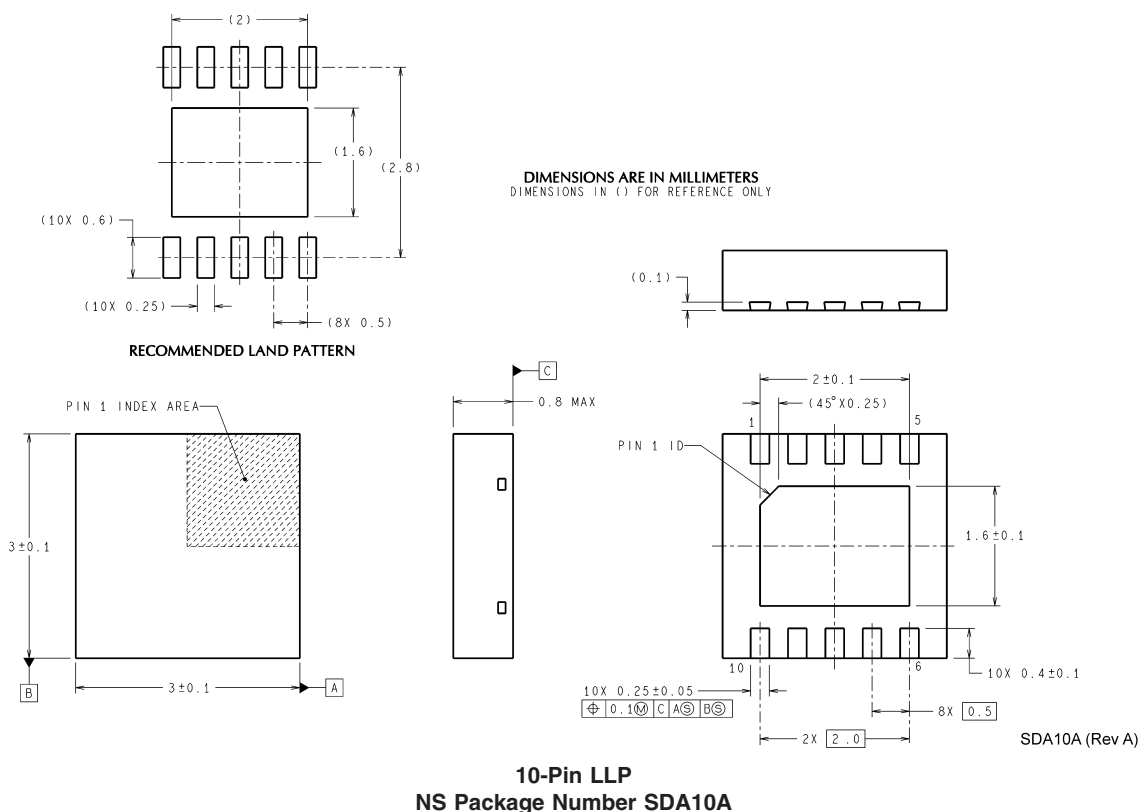
As SET is a sensitive input, crosstalk to that pin should be prevented. Special care should be taken when routing the interface connections. The signals on the serial interface can be more than 60 dB larger than the equivalent LSB at the SET input pin. Crosstalk between the interface bus and  $R_{SET}$  results in disturbance of the output current  $I_{OUT}$  of the LM8342.

For applications requiring a low output current (using high values for  $R_{SET}$  in combination with low DAC settings) special attention should be paid to the parasitic capacitance ( $C_{PAR}$ ) parallel to  $R_{SET}$ . For  $C_{PAR}$  larger than tens of pF, a small (<1 LSB) unwanted ripple at the output current might be obtained. It is recommended to place the  $R_{SET}$  resistor close to the LM8342, in combination with a good board layout to reduce this parasitic capacitance.



**FIGURE 10. LM8342 Evaluation System**

## Physical Dimensions inches (millimeters) unless otherwise noted



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